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12/12/02
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Lary R. Larson

Docket: P-8003

Serial No.: 09/735,826

Group Art: 1765

Filed: December 13, 2000

Examiner: Lynette T. Umez Eronini

Title: METHOD FOR STACKING SEMICONDUCTOR DIE WITHIN AN IMPLANTED MEDICAL DEVICE

RESPONSE TO OFFICE ACTION

DATED OCTOBER 28, 2002

Honorable Commissioner For Patents and Trademarks
Washington, D.C. 20231

Sir:

Reconsideration of the above-identified application is respectfully requested.
Please amend the application as follows:

IN THE CLAIMS:

Please cancel claims 1-21 and enter new claims 22- 25 as follows:

22. A method for forming a stackable wafer for use in an implantable medical device, comprising:

providing a housing;

B1 mounting a semiconductor module inside the housing, wherein said semiconductor module includes first and second semiconductor die in a stacked arrangement, the stacked semiconductor die having circuitry implementing an operational implantable medical device function; and

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